



2826

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q64096

Yoshihiro NAKAJIMA, et al.

Appln. No.: 09/941,744

Group Art Unit: 2826

Confirmation No.: 7388

Examiner: Pershelle L. GREENE

Filed: August 30, 2001

For: SEMICONDUCTOR DEVICE

#9/a
10/22/02

Smith

AMENDMENT UNDER 37 C.F.R. § 1.111

Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated April 24, 2002, please amend the above-identified application as follows:

IN THE TITLE:

Please delete the present title and replace it with the following new title:

SEMICONDUCTOR DEVICE WITH UNEVEN METAL PLATE TO IMPROVE
ADHESION TO MOLDING COMPOUND

IN THE SPECIFICATION:

Page 21, second full paragraph, please replace with the following:

FIGS. 9A and 9B are illustrations showing the semiconductor device 4 of the
embodiment 2 of the present invention, FIG. 9A is a plane view and FIG. 9B is a cross-section
cut along the line VIII-VIII' of FIG. 9A;

10/09/2002 CNGUYEN 00000073 09941744

02 FC:103 72.00 OP
03 FC:102 168.00 OP